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(54) Title: OVERVOLTAGE PROTECTION DEVICE INCLUDING WAFER OF VARISTOR MATERIAL					
(57) Abstract					
<p>An overvoltage protection device includes a first electrode member having a first substantially planar contact surface and a second electrode member having a second substantially planar contact surface facing the first contact surface. A wafer formed of varistor material and having first and second opposed, substantially planar wafer surfaces is positioned between the first and second contact surfaces with the first and second wafer surfaces engaging the first and second contact surfaces, respectively. The contact surfaces may apply a load to the wafer surfaces. Preferably, the electrode members have a combined thermal mass which is substantially greater than a thermal mass of the wafer. The wafer may be formed by slicing a rod of varistor material. The device may include a housing including the first substantially planar contact surface and a sidewall, the housing defining a cavity within which the second electrode is disposed.</p>					

**OVERVOLTAGE PROTECTION DEVICE INCLUDING
WAFER OF VARISTOR MATERIAL**

Field of the Invention

5 The present invention relates to voltage surge protection devices and, more particularly, to a voltage surge protection device including a wafer of varistor material.

Background of the Invention

10 Frequently, excessive voltage is applied across service lines which deliver power to residences and commercial and institutional facilities. Such excess voltage or voltage spikes may result from lightning strikes, for example. The voltage surges are of particular concern in telecommunications 15 distribution centers, hospitals and other facilities where equipment damage caused by voltage surges and resulting down time may be very costly.

Typically, one or more varistors (i.e., voltage dependent resistors) are used to protect a facility from voltage surges. 20 Generally, the varistor is connected directly across an AC input and in parallel with the protected circuit. The varistor has a characteristic clamping voltage such that, responsive to a voltage increase beyond a prescribed voltage, the varistor forms a low resistance shunt path for the overvoltage current that 25 reduces the potential for damage to the sensitive components. Typically, a line fuse may be provided in the protective circuit and this line fuse is blown or weakened by the essentially short circuit created by the shunt path.

Varistors have been constructed according to several designs 30 for different applications. For heavy duty applications (e.g., surge current capability in the range of from about 60 to 100 kA) such as protection of telecommunications facilities, block varistors are commonly employed. A block varistor typically includes a disk shaped varistor element potted in a plastic 35 housing. The varistor disk is formed by pressure casting a metal

oxide material, such as zinc oxide, or other suitable material such as silicon carbide. Copper, or other electrically conductive material, is flame sprayed onto the opposed surfaces of the disk. Ring shaped electrodes are bonded to the coated 5 opposed surfaces and the disk and electrode assembly is enclosed within the plastic housing. Examples of such block varistors include Product No. SIOV-B860K250 available from Siemens Matsushita Components GmbH & Co. KG and Product No. V271BA60 available from Harris Corporation.

10 Another varistor design includes a high energy varistor disk housed in a disk diode case. The diode case has opposed electrode plates and the varistor disk is positioned therebetween. One or both of the electrodes include a spring member disposed between the electrode plate and the varistor disk 15 to hold the varistor disk in place. The spring member or members provide only a relatively small area of contact with the varistor disk.

20 The varistor constructions described above often perform inadequately in service. Often, the varistors overheat and catch fire. Overheating may cause the electrodes to separate from the varistor disk, causing arcing and further fire hazard. There may be a tendency for pinholing of the varistor disk to occur, in turn causing the varistor to perform outside of its specified range. During high current impulses, varistor disks of the prior 25 art may crack due to piezoelectric effect, thereby degrading performance. Failure of such varistors has led to new governmental regulations for minimum performance specifications. Manufacturers of varistors have found these new regulations difficult to meet.

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Summary of the Invention

It is, therefore, an object of the present invention to provide a varistor device having improved resistance to overheating and fire when an overvoltage is applied across the 35 varistor device.

It is a further object of the present invention to provide such a varistor device which exhibits a low inductance and a low resistance when an overvoltage is applied across the varistor device.

5 Moreover, it is another object of the present invention to provide a varistor device of the type including a varistor wafer and that allows substantially uniform current distribution through the wafer and minimizes the occurrence of high current hot spots.

10 In order to provide the foregoing and other objects, the present invention is directed to an overvoltage protection device which provides a number of advantages for safely, durably and consistently handling extreme and repeated overvoltage conditions. The device includes a wafer of varistor material and a pair of 15 electrode members, one of which is preferably a housing, having substantially planar contact surfaces for engaging substantially planar surfaces of the wafer.

20 Preferably, the electrodes have relatively large thermal masses as compared to the thermal mass of the varistor wafer so as to absorb a significant amount of heat from the varistor wafer. In this manner, the device reduces heat induced destruction or degradation of the varistor wafer as well as any tendency for the varistor wafer to produce sparks or flame. The relatively large thermal masses of the electrodes and the substantial contact areas 25 between the electrodes and the varistor wafer also provide a more uniform temperature distribution in the varistor wafer, thereby reducing hot spots and resultant localized depletion of the varistor material.

30 Preferably, the electrodes are mechanically loaded against the varistor wafer. Preferably, biasing means are used to provide and maintain the load. The loading preferably provides a more even current distribution through the varistor wafer. As a result, the device responds to overvoltage conditions more efficiently and predictably, and high current spots which may 35 cause pinholing are more likely to be avoided. Also, the tendency

for the varistor wafer to warp responsive to high current impulses is prevented or reduced by the mechanical reinforcement provided by the electrodes. Moreover, during an overvoltage event, the device would be expected to provide lower inductance and lower 5 resistance because of the more uniform and efficient current distribution through the varistor wafer.

Preferably, the device includes a metal housing and further components configured to prevent or minimize the expulsion of flame, sparks and/or varistor material upon overvoltage failure of 10 the varistor wafer. Preferably, the wafer is formed by slicing the wafer from a rod of the varistor material.

Brief Description of the Drawings

The accompanying drawings which form a part of the 15 specification, illustrate key embodiments of the present invention. The drawings and description together, serve to fully explain the invention. In the drawings,

Figure 1 is an exploded, perspective view of a varistor device according to the present invention;

20 **Figure 2** is a top perspective view of the varistor device of **Figure 1**;

Figure 3 is a cross-sectional view of the varistor device of **Figure 1** taken along the line 3-3 of **Figure 2**;

Figure 4 is a perspective view of a varistor wafer;

25 **Figure 5** is an exploded, perspective view of a varistor device according to a second embodiment of the present invention;

Figure 6 is a top perspective view of the varistor device of **Figure 5**;

30 **Figure 7** is a bottom perspective view of the varistor device of **Figure 5**;

Figure 8 is a view of the varistor device of **Figure 5**, in which the varistor device is mounted in an electrical service utility box;

Figure 9 is an exploded, perspective view of a varistor

device according to a third embodiment of the present invention;

Figure 10 is a top, perspective view of the varistor device of **Figure 9**; and

Figure 11 is a cross-sectional view of the varistor device 5 of **Figure 9** taken along the line 11-11 of **Figure 10**.

Detailed Description of the Preferred Embodiments

The present invention now will be described more fully hereinafter with reference to the accompanying drawings, in which 10 embodiments of the invention are shown. This invention may, however, be embodied in many different forms and should not be construed as limited to the embodiments set forth herein; rather, these embodiments are provided so that this disclosure will be thorough and complete, and will fully convey the scope of the 15 invention to those skilled in the art. In the drawings, like numbers refer to like elements throughout.

With reference to **Figures 1-3**, an overvoltage protection device according to a first embodiment of the present invention is shown therein and designated **100**. The device **100** includes a 20 housing **120** of generally cylindrical shape. The housing is preferably formed of aluminum. However, any suitable conductive metal may be used. The housing has a center wall **122** (**Figure 3**), cylindrical walls **124** extending from the center wall in opposite directions, and a housing electrode ear **129** extending outwardly 25 from the walls **124**. The housing is preferably unitary and axially symmetric as shown. The cylindrical walls **124** and the center wall **122** form cavities **121** on either side of the center wall, each cavity communicating with a respective opening **126**.

A piston-shaped electrode **130** is positioned in each of the 30 cavities **121**. Shafts **134** of the electrodes **130** project outwardly through the respective openings **126**. The electrodes **130** are preferably formed of aluminum. However, any suitable conductive metal may be used. Additionally, and as discussed in greater detail below, a varistor wafer **110**, spring washers **140**, an

insulator ring **150** and an end cap **160** are disposed in each cavity **121**.

In use, the device **100** may be connected directly across an AC or DC input, for example, in an electrical service utility box.

5 Service lines are connected directly or indirectly to the electrode shafts **134** and the housing electrode ear **129** such that an electrical flow path is provided through the electrodes **130**, the varistor wafers **110**, the housing center wall **122** and the housing electrode ear **129**. In the absence of an overvoltage 10 condition, the varistor wafers **110** provide high resistances such that no current flows through the device **100** as it appears electrically as an open circuit. In the event of an overvoltage condition (relative to the design voltage of the device), the resistances of the varistor wafers decrease rapidly, allowing 15 current to flow through the device **100** and create a shunt path for current flow to protect other components of an associated electrical system. The general use and application of overvoltage protectors such as varistors is well known to those of skill in the art and, accordingly, will not be further detailed herein.

20 As will be appreciated from the Figures, the device **100** is axially symmetric, the upper and lower halves of the device **100** being constructed in the same manner. Accordingly, the device **100** will be described hereinafter with respect to the upper portion only, it being understood that such description applies equally to 25 the lower portion.

Turning to the construction of the device **100** in greater detail, the electrode **130** has a head **132** and an integrally formed shaft **134**. As best seen in **Figure 3**, the head **132** has a substantially planar contact surface **132A** which faces a 30 substantially planar contact surface **122A** of the housing center wall **122**. The varistor wafer **110** is interposed between the contact surfaces **122** and **132**. As described in more detail below, the head **132** and the center wall **122** are mechanically loaded against the varistor wafer **110** to ensure firm and uniform

engagement between the surfaces **112** and **132A** and between the surfaces **114** and **122A**. A threaded bore **136** is formed in the end of the shaft **134** to receive a bolt for securing a bus bar or other electrical connector to the electrode **130**.

With reference to **Figure 4**, the varistor wafer **110** has a first substantially planar contact surface **112** and a second, opposed, substantially planar contact surface **114**. As used herein, the term "wafer" means a substrate having a thickness which is relatively small compared to its diameter, length or width dimensions. The varistor wafer **110** is preferably disk shaped. However, the varistor wafer may be formed in other shapes. The thickness **T** and the diameter **D** of the varistor **110** will depend on the varistor characteristics desired for the particular application. Preferably, and as shown, the varistor wafer **110** includes a wafer **111** of varistor material coated on either side with a conductive coating **112A**, **114A**, so that the exposed surfaces of the coatings **112A** and **114A** serve as the contact surfaces **112** and **114**. Preferably, the coatings **112A**, **114A** are formed of aluminum, copper or solder.

The varistor material may be any suitable material conventionally used for varistors, namely, a material exhibiting a nonlinear resistance characteristic with applied voltage. Preferably, the resistance becomes very low when a prescribed voltage is exceeded. The varistor material may be a doped metal oxide or silicon carbide, for example. Suitable metal oxides include zinc oxide compounds.

The varistor material wafer **111** is preferably formed by first forming a rod or block (not shown) of the varistor material and then slicing the wafer **111** from the rod using a diamond cutter or other suitable device. The rod may be formed by extruding or casting a rod of the varistor material and thereafter sintering the rod at high temperature in an oxygenated environment. This method of forming allows for the formation of a wafer having more planar surfaces and less warpage or profile fluctuation than would

typically be obtained using a casting process. The coatings **112A**, **114A** are preferably formed of aluminum or copper and may be flame sprayed onto the opposed sides of the wafer **111**.

While the device **100** as shown in **Figure 1** includes two spring washers **140**, more or fewer may be used. Each spring washer **140** includes a hole **142** which receives the shaft **134** of the electrode **130**. Each spring washer **140** surrounds a portion of the shaft **134** immediately adjacent to the head **132** and abuts the rear face of the head **132** or the preceding spring washer **140**. Each hole **142** preferably has a diameter of between about 0.012 and 0.015 inch greater than the corresponding diameter of the shaft **134**. The spring washers **140** are preferably formed of a resilient material and, more preferably, the spring washers **140** are Belleville washers formed of spring steel.

The insulator ring **150** overlies and abuts the outermost spring washer **140**. The insulator ring **150** has a hole **152** formed therein which receives the shaft **134**. Preferably, the diameter of the hole **152** is between about 0.005 and 0.007 inch greater than the corresponding diameter of the shaft **134**. The insulator ring **150** is preferably formed of an electrically insulating material having high melting and combustion temperatures. More preferably, the insulator ring **150** is formed of polycarbonate, ceramic or a high temperature polymer.

The end cap **160** overlies and abuts the insulator ring **150**. The end cap **160** has a hole **162** which receives the shaft **134**. Preferably, the diameter of the hole **162** is between about 0.500 and 0.505 inch greater than the corresponding diameter of the shaft **134** to provide a sufficient clearance gap **165** (**Figure 2**) to avoid electrical arcing between the end cap **160** and the electrode shaft **134** during non-overshoot conditions. Threads **168** on the peripheral wall of the end cap **160** engage complementary threads **128** formed in the housing **120**. Holes **163** are formed in the end cap to receive a tool (not shown) for rotating the end cap **160**.

with respect to the housing 120. Other means for receiving a tool, for example, a hex-shaped slot, may be provided in place of or in addition to the holes 163. The end cap 160 has an annular ridge 167 which is received within the inner diameter of the 5 housing 120. The housing 120 includes a rim 127 to prevent overinsertion of the end cap 150. Preferably, the end cap is formed of aluminum.

As noted above and as best shown in **Figure 3**, the electrode head 132 and the center wall 122 are loaded against the varistor wafer 110 to ensure firm and uniform engagement between the 10 surfaces 112 and 132A and between the surfaces 114 and 122A. This aspect of the device 100 may be appreciated by considering a method according to the present invention for assembling the device 100. The varistor wafer 110 is placed in the cavity 121 15 such that the wafer surface 114 engages the contact surface 122A. The electrode 130 is inserted into the cavity 121 such that the contact surface 132A engages the varistor wafer surface 112. The spring washers 140 are slid down the shaft 134 and placed over the head 132. The insulator ring 150 is slid down the shaft 134 and 20 over the outermost spring washer 140. The end cap 160 is slid down the shaft 134 and screwed into the opening 126 by engaging the threads 168 with the threads 128 and rotating.

Once the device 100 has been assembled as just described, the end cap 160 is selectively torqued to force the insulator ring 150 25 downwardly so that it partially deflects the spring washers 140. The loading of the end cap 160 onto the insulator ring 150 and from the insulator ring onto the spring washers 140 is in turn transferred to the head 132. In this way, the varistor wafer 110 is sandwiched (clamped) between the head 132 and the center wall 122. 30

Preferably, the device 100 is designed such that the desired loading will be achieved when the spring washers 150 are only partially deflected and, more preferably, when the spring washers

are fifty percent (50%) deflected. In this way, variations in manufacturing tolerances of the other components of the device 100 may be accommodated.

The amount of torque applied to the end cap 160 will depend 5 on the desired amount of load between the varistor wafer 110 and the head 132 and the center wall 122. Preferably, the amount of the load of the head and the center wall against the varistor wafer is at least 264 lbs. More preferably, the load is between about 528 and 1056 lbs. Preferably, the coatings 112A and 114A 10 have a rough initial profile and the compressive force of the loading deforms the coatings to provide more continuous engagements between the coatings and the contact surfaces 122A and 132A.

Alternatively, or additionally, the desired load amount may 15 be obtained by selecting an appropriate number and or sizes of spring washers 140. The spring washers each require a prescribed amount of load to deflect a prescribed amount and the overall load will be the sum of the spring deflection loads.

Preferably, the area of engagement between the contact 20 surface 132A and the varistor wafer surface 112 is at least 1.46 square inches. Likewise, the area of engagement between the contact surface 122A and the varistor wafer surface 114 is preferably at least 1.46 square inches. Preferably, the electrode head 132 has a thickness **H** of at least 0.50 inch. The center wall 25 122 preferably has a thickness **W** of at least 0.25 inch.

The combined thermal mass of the housing 120 and the electrode 130 should be substantially greater than the thermal mass of the varistor wafer 110. As used herein, the term "thermal mass" means the product of the specific heat of the material or 30 materials of the object (e.g., the varistor wafer 110) multiplied by the mass or masses of the material or materials of the object. That is, the thermal mass is the quantity of energy required to raise one gram of the material or materials of the object by one degree centigrade times the mass or masses of the material or

materials in the object. Preferably, the thermal masses of each of the electrode head **132** and the center wall **122** are substantially greater than the thermal mass of the varistor wafer **110**. Preferably, the thermal masses of each of the electrode head **132** and the center wall **122** are at least two (2) times the thermal mass of the varistor wafer **110**, and, more preferably, at least ten (10) times as great.

The overvoltage protection device **100** provides a number of advantages for safely, durably and consistently handling extreme and repeated overvoltage conditions. The relatively large thermal masses of the housing **120** and the electrode **130** serve to absorb a relatively large amount of heat from the varistor wafer **110**, thereby reducing heat induced destruction or degradation of the varistor wafer as well as reducing any tendency for the varistor wafer to produce sparks or flame. The relatively large thermal masses and the substantial contact areas between the electrode and the housing and the varistor wafer provide a more uniform temperature distribution in the varistor wafer, thereby minimizing hot spots and resultant localized depletion of the varistor material.

The loading of the electrode and the housing against the varistor wafer as well as the relatively large contact areas provide a more even current distribution through the varistor wafer **10**. As a result, the device **100** responds to overvoltage conditions more efficiently and predictably, and high current spots which may cause pinholing are more likely to be avoided. The tendency for the varistor wafer **110** to warp responsive to high current impulses is reduced by the mechanical reinforcement provided by the loaded head **132** and center wall **122**. The spring washers may temporarily deflect when the varistor wafer expands and return when the varistor wafer again contracts, thereby maintaining the load throughout and between multiple overvoltage events. Moreover, during an overvoltage event, the device **100** will generally provide lower inductance and lower resistance

because of the more uniform and efficient current distribution through the varistor wafer.

The device **100** also serves to prevent or minimize the expulsion of flame, sparks and/or varistor material upon overvoltage failure of the varistor wafer **110**. The strength of the metal housing as well as the configuration of the electrode **130**, the insulator ring **150** and the end cap **160** serve to contain the products of a varistor wafer failure. In the event that the varistor destruction is so severe as to force the electrode **130** away from the varistor and melt the insulator ring **150**, the electrode **130** will be displaced into direct contact with the end cap **160**, thereby shorting the electrode **130** and the housing **120** and causing an in-line fuse (not shown) to blow.

While the housing **120** is illustrated as cylindrically shaped, the housing may be shaped differently. The lower half of the device **100** may be deleted, so that the device **100** includes only an upper housing wall **124** and a single varistor wafer, electrode, spring washer or set of spring washers, insulator ring and end cap.

Methods for forming the several components of the device will be apparent to those of skill in the art in view of the foregoing description. For example, the housing **120**, the electrode **130**, and the end cap **160** may be formed by machining, casting or impact molding. Each of these elements may be unitarily formed or formed of multiple components fixedly joined, by welding, for example.

With reference to **Figures 5-8**, a varistor device **200** according to a second embodiment of the present invention is shown therein. The varistor device **200** includes elements **210**, **230**, **240** and **260** corresponding to elements **110**, **130**, **140** and **160**, respectively, of the varistor device **100**. The varistor device **200** differs from the varistor device **100** in that the device **200** includes only a single varistor wafer **210** and corresponding components. The varistor device **200** includes a housing **220** which is the same as the housing **120** except as follows. The housing **220**

defines only a single cavity **221**, and has only a single surrounding wall **224** extending from the center (or end) wall **222** thereof. Also, the housing **220** has a threaded stud **229** (**Figure 7**) extending from the lower surface of the center (or end) wall **222** rather than a sidewardly extending electrode ear corresponding to the electrode ear **129**. The stud **229** is adapted to engage a threaded bore of a conventional electrical service utility box or the like.

The varistor device **200** further differs from the varistor device **100** in the provision of an insulator ring **251**. The insulator ring **251** has a main body ring **252** corresponding to the insulator ring **150**. The ring **251** further includes a collar **254** extending upwardly from the main body ring **252**. The inner diameter of the collar **254** is sized to receive the shaft **234** of the electrode **230**, preferably in clearance fit. The outer diameter of the collar **254** is sized to pass through the hole **262** of the end cap **260** with a prescribed clearance gap **265** (**Figure 6**) surrounding the collar **254**. The gap **265** allows clearance for inserting the shaft **134** and may be omitted. The main body ring **252** and the collar **254** are preferably formed of the same material as the insulator ring **150**. The main body ring **252** and the collar **254** may be bonded or integrally molded.

With reference to **Figure 8**, the varistor device **200** is shown therein mounted in an electrical service utility box **10**. The varistor device **200** is mounted on a metal platform **12** electrically connected to earth ground. The electrode stud **229** engages and extends through a threaded bore **12A** in the platform **12**. A bus bar **16**, electrically connected a first end of a fuse **14**, is secured to the electrode shaft **234** by a threaded bolt **18** inserted into the threaded bore **236** of the electrode **230**. A second end of the fuse may be connected to an electrical service line or the like. As shown in **Figure 8**, a plurality of varistor devices **200** may be connected in parallel in a utility box **10**.

With reference to **Figures 9-11**, a varistor device **300** according to a third embodiment of the present invention is shown therein. The varistor device **300** includes elements **310**, **330**, **340** and **351** corresponding to elements **210**, **230**, **240** and **251**, respectively. The varistor device **300** also includes a flat metal washer **345** interposed between the uppermost spring washer **340** and the insulator ring **351**, the shaft **334** extending through a hole **346** formed in the washer **345**. The washer **345**, which may be incorporated into the devices **100**, **200**, serves to distribute the mechanical load of the uppermost spring washer **340** to prevent the spring washer from cutting into the insulator ring **351**. The housing **320** is the same as the housing **220** except as follows.

The housing **320** of device **300** does not have a rim corresponding to the rim **127** or threads corresponding to the threads **128**. Also, the housing **320** has an internal annular slot **323** formed in the surrounding sidewall **324** and extending adjacent the opening **326** thereof.

The varistor device **300** also differs from the varistor devices **100**, **200** in the manner in which the electrode **330** and the center wall **322** are loaded against the varistor wafer **310**. In place of the end caps **160**, **260**, the varistor device **300** has an end cap **360** and a resilient clip **370**. The clip **370** is partly received in the slot **323** and partly extends radially inwardly from the inner wall of the housing **320** to limit outward displacement of the end cap **360**. The clip **370** is preferably formed of spring steel. The end cap **360** is preferably formed of aluminum.

The varistor device **300** may be assembled in the same manner as the varistor devices **100**, **200** except as follows. The end cap **360** is placed over the shaft **334** and the collar **354**, each of which are received in a hole **362**. The washer **345** is placed over the shaft **334** prior to placing the insulator ring **351**. A jig (not shown) or other suitable device is used to force the end cap **360** down, in turn deflecting the spring washers **340**. While the end

cap 360 is still under the load of the jig, the clip 370 is compressed, preferably by engaging apertures 372 with pliers or another suitable tool, and inserted into the slot 323. The clip 370 is then released and allowed to return to its original 5 diameter, whereupon it partly fills the slot and partly extends radially inward into the cavity 321 from the slot 323. The clip 370 and the slot 323 thereby serve to maintain the load on the end cap 360.

Means other than those described above may be used to load 10 the electrode and housing against the varistor wafer. For example, the electrode and end cap may be assembled and loaded, and thereafter secured in place using a staked joint.

In each of the aforescribed devices 100, 200, 300, multiple 15 varistor wafers (not shown) may be stacked and sandwiched between the electrode head and the center wall. The outer surfaces of the uppermost and lowermost varistor wafers would serve as the wafer contact surfaces. However, the properties of the varistor wafer are preferably modified by changing the thickness of a single 20 varistor wafer rather than stacking a plurality of varistor wafers.

As discussed above, the spring washers 140 are preferably Belleville washers. Belleville washers may be used to apply relatively high loading without requiring substantial axial space. However, other types of biasing means may be used in addition to 25 or in place of the Belleville washer or washers. Suitable alternative biasing means include one or more coil springs, wave washers or spiral washers.

The foregoing is illustrative of the present invention and is not to be construed as limiting thereof. Although a few 30 exemplary embodiments of this invention have been described, those skilled in the art will readily appreciate that many modifications are possible in the exemplary embodiments without materially departing from the novel teachings and advantages of this invention. Accordingly, all such modifications are intended

to be included within the scope of this invention as defined in the Claims. In the Claims, means-plus-function clauses are intended to cover the structures described herein as performing the recited function and not only structural equivalents but also 5 equivalent structures. Therefore, it is to be understood that the foregoing is illustrative of the present invention and is not to be construed as limited to the specific embodiments disclosed, and that modifications to the disclosed embodiments, as well as other embodiments, are intended to be included within the scope 10 of the appended Claims. The invention is defined by the following Claims, with equivalents of the Claims to be included therein.

THE CLAIMS DEFINING THE INVENTION ARE AS FOLLOWS:

1. An overvoltage protection device including:
 - 5 a) a housing including a first substantially planar electrical contact surface and an electrically conductive sidewall, said housing defining a cavity therein and having an opening in communication with said cavity;
 - 10 b) an electrode member including a second substantially planar electrical contact surface facing said first electrical contact surface and disposed within said cavity, a portion of said electrode member extending out of said cavity and through said opening; and
 - 15 c) a wafer formed of varistor material and having first and second opposed, substantially planar wafer surfaces, said wafer positioned within said cavity and between said first and second contact electrical surfaces with said first and second wafer surfaces engaging said first and second electrical contact surfaces, respectively.
2. The device of Claim 1 wherein said first and second electrical contact surfaces apply a load to said first and second wafer surfaces.
3. The device of Claim 2 wherein said load is at least 264 lbs.
4. The device of Claim 2 wherein said load is between about 528 and 1056 lbs.
- 25 5. The device of Claim 2 including adjustable means maintaining said load such that the amount of said load may be selectively adjusted.
6. The device of Claim 2 including biasing means for maintaining said load.
- 30 7. The device of Claim 6 wherein said biasing means includes a spring member biasing at least one of said first and second electrical contact surfaces against said wafer.
- 35 8. The device of Claim 7 including a plurality of spring members biasing at least one of said first and second electrical contact surfaces against said wafer.



9. The device of Claim 7 wherein said spring member includes a spring washer.

10. The device of Claim 7 wherein said spring member includes a Belleville washer.

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11. The device of Claim 2 including an end cap positioned in said opening, said end cap maintaining said load.

10 12. The device of Claim 11 including a clip operative to limit displacement between said end cap and said housing to maintain said load.

13. The device of Claim 12 wherein said housing includes a slot formed therein and said clip engages said slot.

15 14. The device of Claim 11 wherein said housing includes a threaded portion and said end cap includes a threaded portion engaging said housing threaded portion whereby said end cap is operable to selectively adjust and maintain said load.

20 15. The device of Claim 11 including a spring member interposed between said end cap and said wafer.

16. The device of Claim 1 including an electrically insulating member interposed between said second electrical contact surface and said opening.

25 17. The device of Claim 1 including an end cap positioned in said opening and having a hole formed therein, wherein said electrode member includes a head positioned in said cavity between said end cap and said first electrical contact surface and a shaft extending out of said cavity and through said end cap hole.

30 18. The device of Claim 17 including an electrically insulating ring member having a hole formed therein, said insulating ring member interposed between said head and said end cap, wherein said shaft extends through said insulating ring member hole.

35 19. The device of Claim 18 wherein said insulating ring member includes a main body ring portion and a projecting collar, said projecting collar surrounding said shaft and extending through said end cap hole.



20. The device of Claim 17 including a spring washer having a hole formed therein, said spring washer interposed between said head and said end cap, wherein said shaft extends through said spring washer hole.

5 21. The device of Claim 17 including an electrically insulating ring member and a spring washer, said electrically insulating ring member having a hole formed therein and interposed between head and said end cap, said spring washer having a hole formed therein and interposed between head and said electrically insulating ring member, wherein said shaft extends through each of said electrically insulating ring member hole and said spring washer hole.

10 22. The device of Claim 1 wherein said housing and said electrode member have a combined thermal mass which is substantially greater than a thermal mass of said wafer.

15 23. The device of Claim 22 wherein said housing includes an electrode and said electrode member includes a head, each of said electrode wall and said head contacting one of said wafer surfaces and having a thermal mass which is substantially greater than said wafer thermal mass.

20 24. The device of Claim 23 wherein said thermal masses of said electrode wall and said head are each at least twice said wafer thermal mass.

25 25. The device of Claim 23 wherein said thermal masses of said electrode wall and said head are each at least ten times said wafer thermal mass.

26. The device of Claim 1 wherein said housing is formed of metal.

27. The device of Claim 1 wherein said wafer is formed by slicing a rod of varistor material.

30 28. The device of Claim 27 wherein said rod is formed by at least one of extruding and casting.

35 29. The device of Claim 27 wherein said varistor material is selected from the group consisting of a metal oxide compound and silicon carbide.

30. The device of Claim 27 wherein said wafer includes a coating of conductive



metal on at least one of said first and second wafer surfaces.

31. The device of Claim 27 wherein said wafer has a substantially circular peripheral edge and each of said first and second disk surfaces are substantially coextensive with said circular peripheral edge.

32. The device of Claim 1 wherein each of said first and second electrical contact surfaces is continuous and substantially free of voids.

10 33. An overvoltage protection device including:

a) a housing including an electrode wall and a sidewall, said central wall and said sidewall defining a cavity and an opening in communication with said cavity, said electrode wall having a thermal mass and a first substantially planar contact surface;

b) an electrode member including a head positioned in said cavity and a shaft extending out of said cavity and through said opening, said head having a thermal mass and a substantially planar second contact surface facing said first contact surface;

20 c) a wafer formed of varistor material and having first and second opposed, substantially planar wafer surfaces, said wafer positioned within said cavity and between said first and second contact surfaces with said first and second wafer surfaces engaging said first and second contact surfaces, respectively, said wafer having a thermal mass;

25 d) an end cap positioned in said opening, said end cap having a hole through which said shaft extends;

30 e) a spring member interposed between said end cap and said head, and said spring member biasing at least one of said electrode wall and said electrode member against said wafer to apply a load to said first and second wafer surfaces; and

35 f) wherein each of said head thermal mass and said electrode wall thermal mass is substantially greater than said thermal mass of said wafer.

34. The device of Claim 33 wherein said load is at least 264 lbs.



35. The device of Claim 33 wherein said thermal masses of said electrode wall and said head are each at least ten times said wafer thermal mass.

5 36. The device of Claim 33 wherein said wafer is formed by slicing a rod of said varistor material.

10 37. The device of Claim 33 including a clip and wherein said housing includes a slot formed therein, said clip cooperative with said slot to limit displacement of said end cap relative to said housing and to maintain said load.

15 38. The device of Claim 33 wherein said housing includes a threaded portion and said end cap includes a threaded portion engaging said housing threaded portion whereby said end cap is operable to selectively adjust and maintain said load.

20 39. The device of Claim 33 including an electrically insulating ring member, said insulator ring member having a hole formed therein and interposed between said head and said end cap, said spring member having a hole formed therein and interposed between head and said insulating ring member whereby said spring member biases said head against said wafer, wherein said shaft extends through each of said insulating ring member hole and said spring member hole.

25 40. The device of Claim 39 wherein said insulating ring member includes a main body ring portion and a projecting collar, said projecting collar surrounding said shaft and extending through said end cap hole.

30 41. An overvoltage protection device for use with a varistor wafer of the type having first and second opposed, substantially planar wafer surfaces, said device including:

a) a housing including a first substantially planar electrical contact surface and an electrically conductive sidewall, said housing defining a cavity therein and having an opening in communication with said cavity; and

35 b) an electrode member including a second substantially planar electrical contact surface facing said first contact surface and disposed within said cavity, a portion of said electrode extending out of said cavity and through said opening, said



housing and said electrode member relatively arranged and configured to receive the wafer within said cavity such that the wafer is positioned between said first and second electrical contact surfaces with said first and second electrical contact surfaces engaging the first and second wafer surfaces, respectively.

5

42. An overvoltage protection device including:

10 a) a first electrode member having a first substantially planar contact surface;

b) a second electrode member having a second substantially planar contact surface facing said first contact surface;

15 c) a wafer formed of varistor material and having first and second opposed, substantially planar wafer surfaces, said wafer positioned between said first and second contact surfaces with said first and second wafer surfaces engaging said first and second contact surfaces, respectively; and

20 d) biasing means biasing at least one of said first and second contact surfaces against said wafer to apply a load to said first and second wafer surfaces.

e) wherein said load is at least 264 lbs.

25 43. The device of Claim 42 wherein said load is between about 528 and 1056 lbs.

44. The device of Claim 42 wherein said biasing means includes a spring member biasing at least one of said first and second electrode members against said wafer.

30 45. The device of Claim 42 including a plurality of spring members biasing at least one of said first and second electrode members against said wafer.

46. The device of Claim 42 wherein said spring member includes a spring washer.

35 47. The device of Claim 47 wherein said spring member includes a Belleville washer.

48. A method for assembling an overvoltage protection device, said method



including the steps of:

5 a) providing a first electrode member having a first substantially planar contact surface;

10 b) providing a second electrode member having a second substantially planar contact surface facing the first contact surface;

c) providing a biasing means;

15 d) placing a wafer formed of varistor material and having first and second opposed, substantially planar wafer surfaces between the first and second contact surfaces such that the first and second wafer surfaces engage the first and second contact surfaces, respectively;

20 e) biasing the biasing means to apply a load between the first and second contact surfaces and against the first and second wafer surfaces; and

f) maintaining the load during an overvoltage event.

25 g) wherein said load is at least 264 lbs.

49. The method of Claim 49 wherein the biasing means includes a spring member and said step of biasing includes deflecting the spring member.

50. An overvoltage protection device including:

30 a) a housing including a first substantially planar contact surface and a sidewall, said housing defining a cavity therein and having an opening in communication with said cavity;

35 b) an electrode member including a substantially planar second contact surface facing said first contact surface and disposed within said cavity, a portion of said electrode member extending out of said cavity and through said opening; and

c) a wafer formed of varistor material and having first and second



opposed, substantially planar wafer surfaces, said wafer positioned within said cavity and between said first and second contact-surfaces with said first and second wafer surfaces engaging said first and second contact surfaces, respectively;

5

d) wherein said first and second contact surfaces apply a load to said first and second wafer surfaces; and

10

51 The device of Claim 51 wherein said load is between about 528 and 1056 lbs.

52. An overvoltage protection device including:

15

a) a housing including a first substantially planar contact surface and a sidewall, said housing defining a cavity therein and having an opening in communication with said cavity;

20

b) an electrode member including a substantially planar second contact surface facing said first contact surface and disposed within said cavity, a portion of said electrode member extending out of said cavity and through said opening; and

25

c) a wafer formed of varistor material and having first and second opposed, substantially planar wafer surfaces, said wafer positioned within said cavity and between said first and second contact-surfaces with said first and second wafer surfaces engaging said first and second contact surfaces, respectively;

30

d) wherein said first and second contact surfaces apply a load to said first and second wafer surfaces, said device includes biasing means for maintaining said load and including a spring member biasing at least one of said first and second contact surfaces against said wafer;

e) wherein said spring member includes a spring washer.

35

53. The device of Claim 53 wherein said spring member includes a Belleville washer.



54. An overvoltage protection device including:

a) a housing including a first substantially planar contact surface and a sidewall, said housing defining a cavity therein and having an opening in communication with said cavity;

b) an electrode member including a substantially planar second contact surface facing said first contact surface and disposed within said cavity, a portion of said electrode member extending out of said cavity and through said opening; and

c) a wafer formed of varistor material and having first and second opposed, substantially planar wafer surfaces, said wafer positioned within said cavity and between said first and second contact surfaces with said first and second wafer surfaces engaging said first and second contact surfaces, respectively;

d) wherein said first and second contact surfaces apply a load to said first and second wafer surfaces and said device further including a clip operative to limit displacement between said end cap and said housing to maintain said load.

55. The device of Claim 55 wherein said housing includes a slot formed therein and said clip engages said slot.

56. An overvoltage protection device including:

a) a housing including a first substantially planar contact surface and a sidewall, said housing defining a cavity therein and having an opening in communication with said cavity;

b) an electrode member including a substantially planar second contact surface facing said first contact surface and disposed within said cavity, a portion of said electrode member extending out of said cavity and through said opening; and

c) a wafer formed of varistor material and having first and second opposed, substantially planar wafer surfaces, said wafer positioned within said cavity and between said first and second contact surfaces with said first and second wafer surfaces engaging said first and second contact surfaces, respectively;



5 d) an end cap positioned in said opening and having a hole formed therein, wherein said electrode member includes a head positioned in said cavity between said end cap and said first contact surface and a shaft extending out of said cavity and through said end cap hole; and

10 e) an electrically insulating ring member having a hole formed therein, said insulating ring member interposed between said head and said end cap, wherein said shaft extends through said insulating ring member hole;

15 f) wherein said insulating ring member includes a main body ring portion and a projecting collar, said projecting collar surrounding said shaft and extending through said end cap hole.

20 57. An overvoltage protection device including:

25 a) a housing including a first substantially planar contact surface and a sidewall, said housing defining a cavity therein and having an opening in communication with said cavity;

30 b) an electrode member including a substantially planar second contact surface facing said first contact surface and disposed within said cavity, a portion of said electrode member extending out of said cavity and through said opening; and

35 c) a wafer formed of varistor material and having first and second opposed, substantially planar wafer surfaces, said wafer positioned within said cavity and between said first and second contact surfaces with said first and second wafer surfaces engaging said first and second contact surfaces, respectively;

40 d) wherein said housing and said electrode member have a combined thermal mass which is substantially greater than a thermal mass of said wafer; and

45 e) wherein said housing includes an electrode and said electrode member includes a head, each of said electrode wall and said head contacting one of said wafer surfaces and having a thermal mass which is substantially greater than said wafer thermal mass.



58. The device of Claim 58 wherein said thermal masses of said electrode wall and said head are each at least twice said wafer thermal mass.

59. The device of Claim 58 wherein said thermal masses of said electrode wall and said head are each at least ten times said wafer thermal mass.

60. An overvoltage protection device including:

10 a) a first electrode member having a first substantially planar contact surface;

b) a second electrode member having a second substantially planar contact surface facing said first contact surface;

15 c) a wafer formed of varistor material and having first and second opposed, substantially planar wafer surfaces, said wafer positioned between said first and second contact surfaces with said first and second wafer surfaces engaging said first and second contact surfaces, respectively; and

20 d) biasing means biasing at least one of said first and second contact surfaces against said wafer to apply a load to said first and second wafer surfaces;

e) wherein said spring member includes a spring washer.

25 61. The device of Claim 61 wherein said spring member includes a Belleville washer.

62. A method for assembling an overvoltage protection device, said method including the steps of:

30 a) providing a first electrode member having a first substantially planar contact surface;

b) providing a second electrode member having a second substantially planar contact surface facing the first contact surface;

c) providing a biasing means including a spring member, said spring



member including a spring washer;

5 d) placing a wafer formed of varistor material and having first and second opposed, substantially planar wafer surfaces between the first and second contact surfaces such that the first and second wafer surfaces engage the first and second contact surfaces, respectively;

10 e) biasing the biasing means to apply a load between the first and second contact surfaces and against the first and second wafer surfaces, said step of biasing including deflecting the spring member; and

15 f) maintaining the load during an overvoltage event.

63. The device of Claim 63 wherein said spring member includes a Belleville
15 washer.

Dated this 25th day of September 2002

TYCO ELECTRONICS CORPORATION

By their Patent Attorneys

20 GRIFFITH HACK



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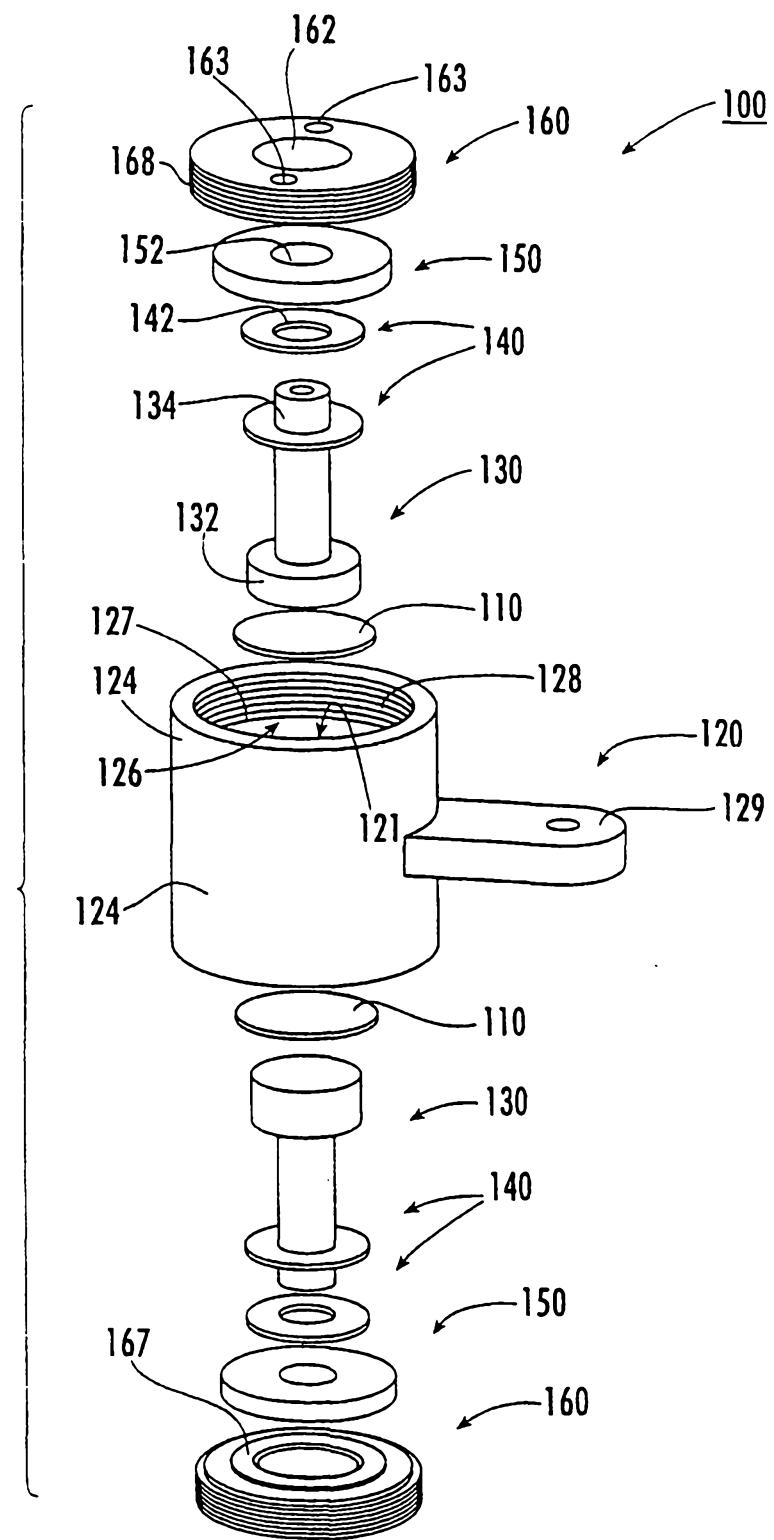


FIG. I.

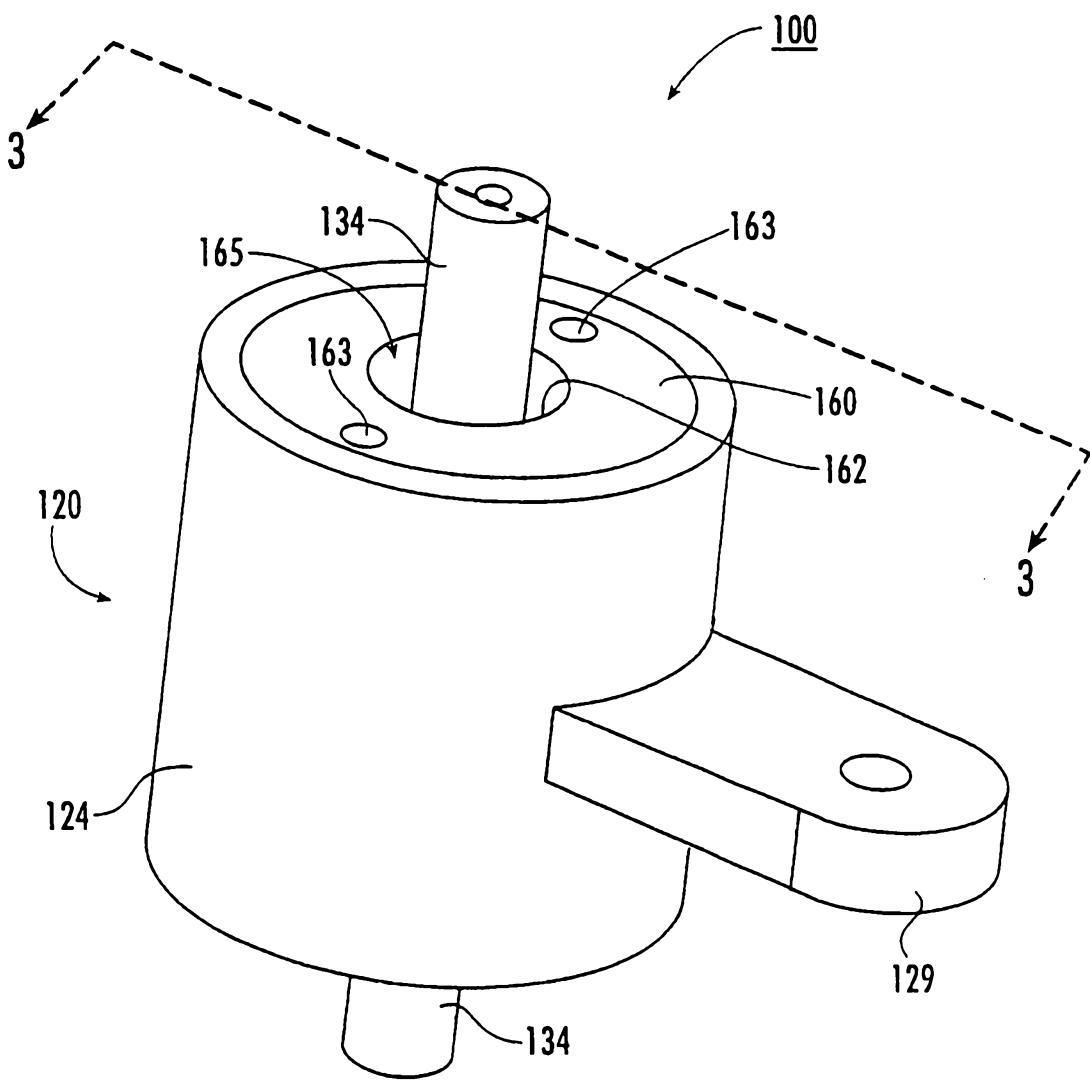


FIG. 2.

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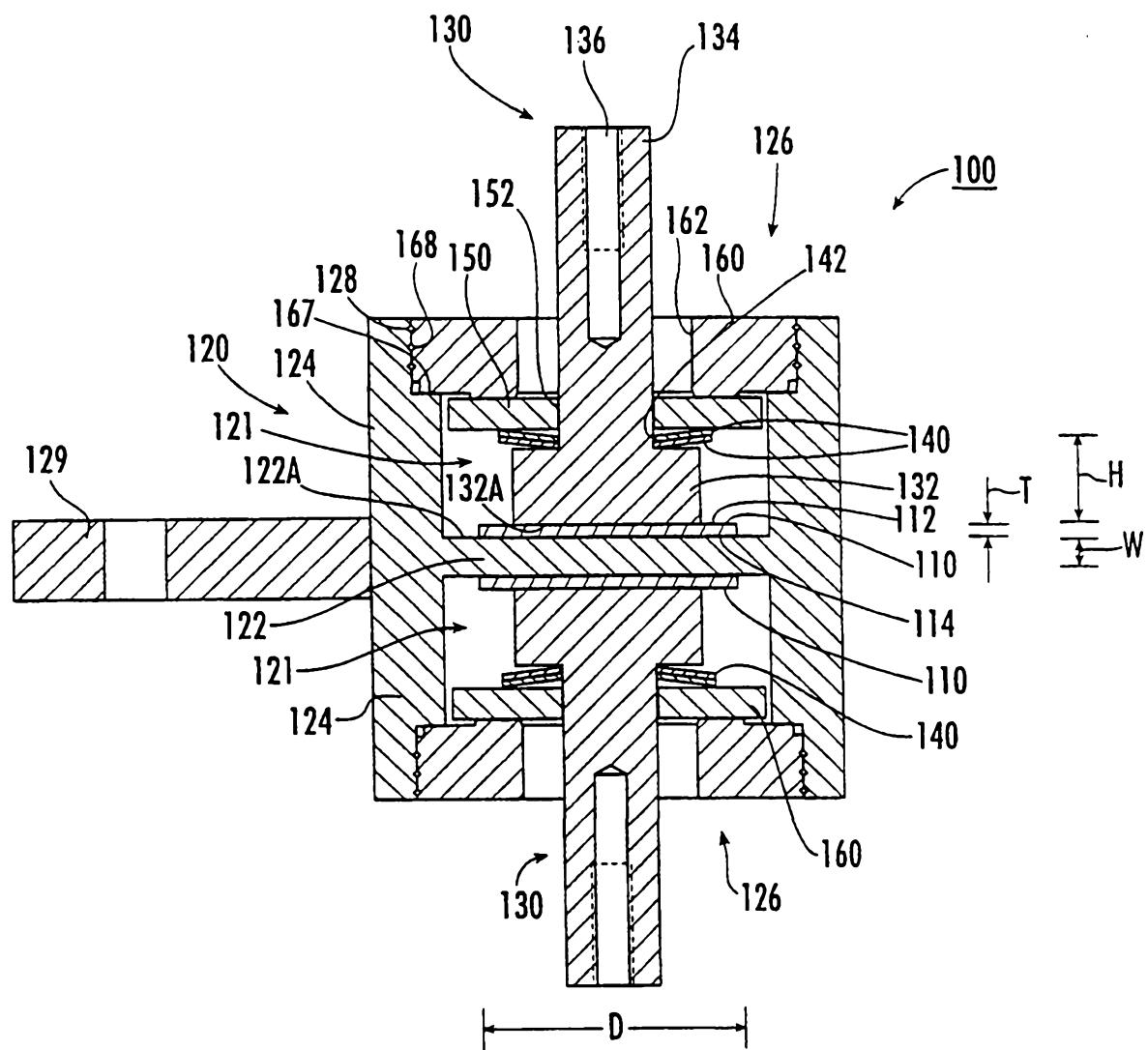


FIG. 3.

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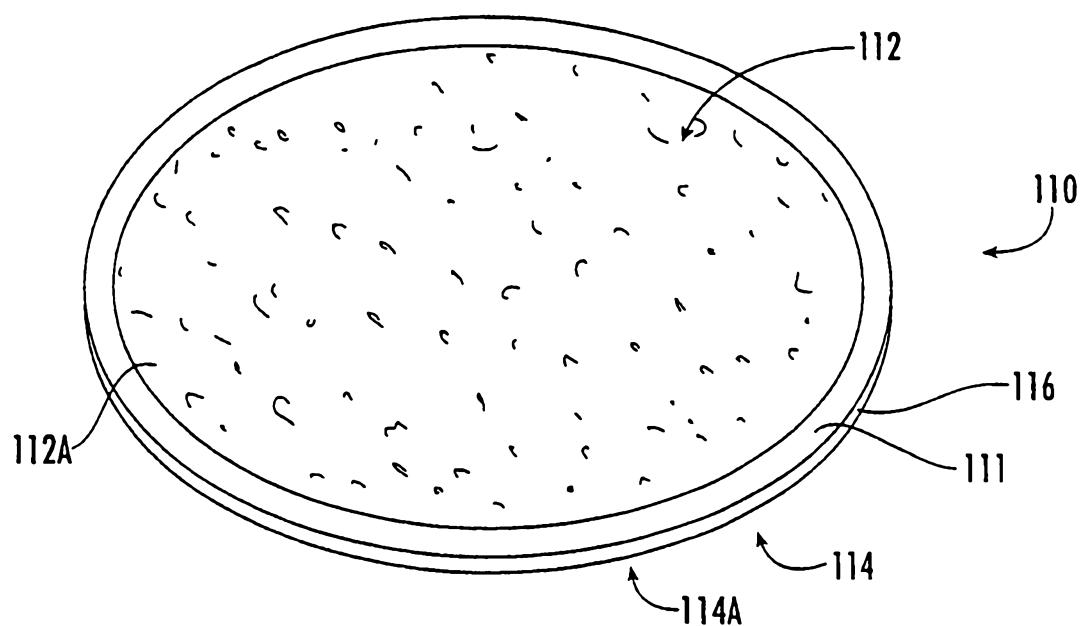


FIG. 4.

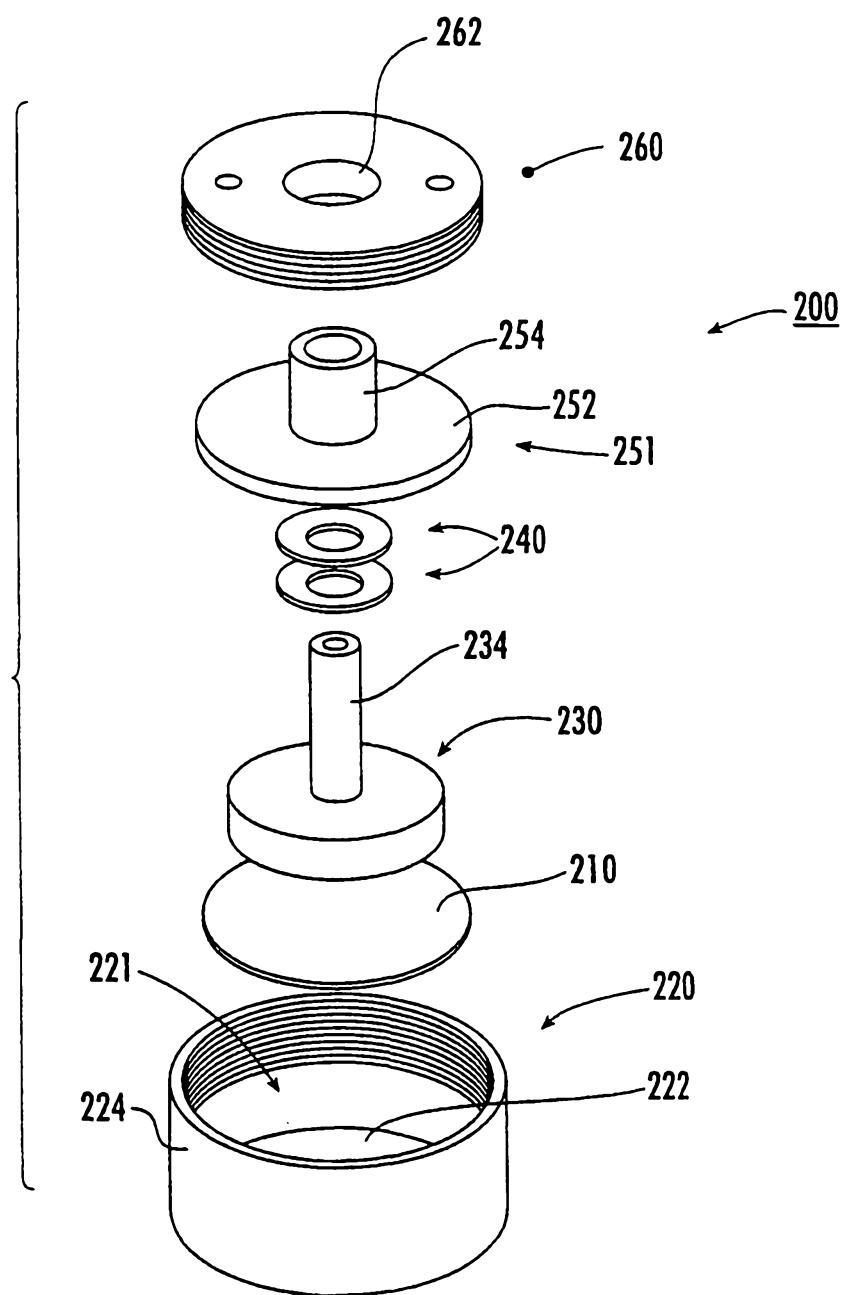


FIG. 5.

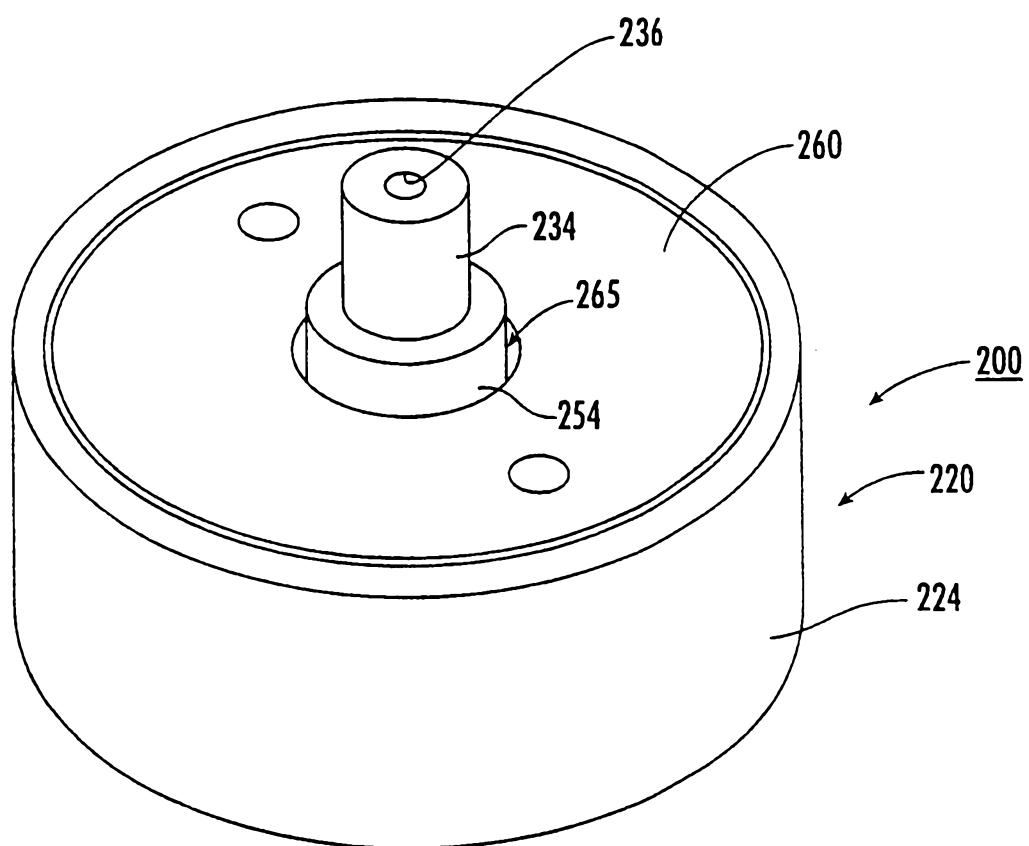


FIG. 6.

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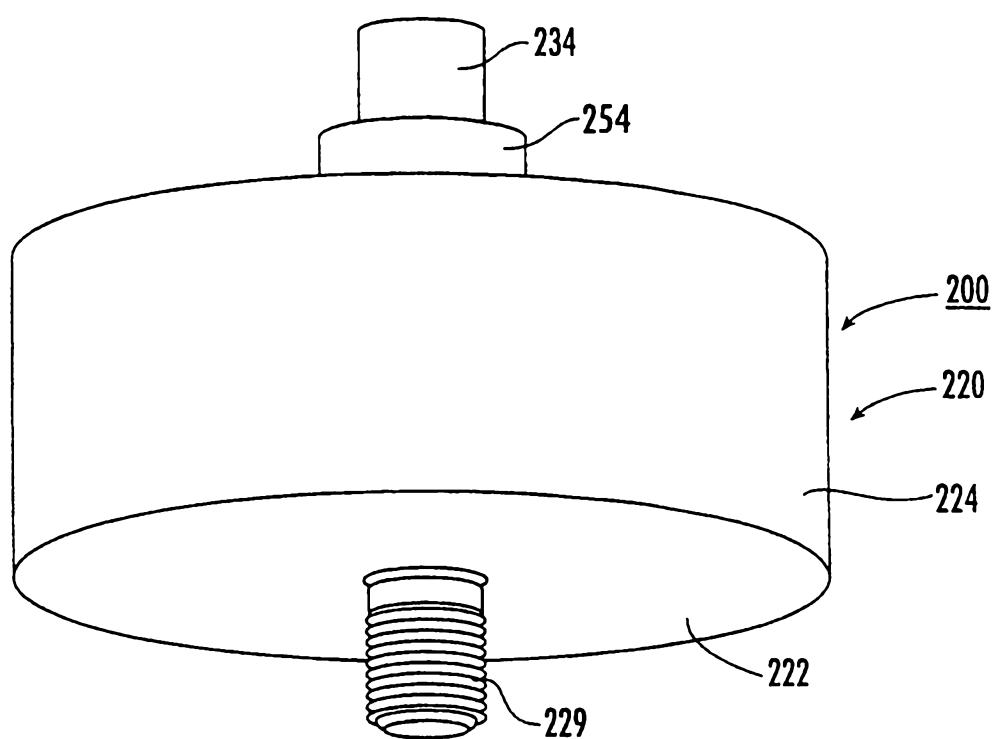


FIG. 7.

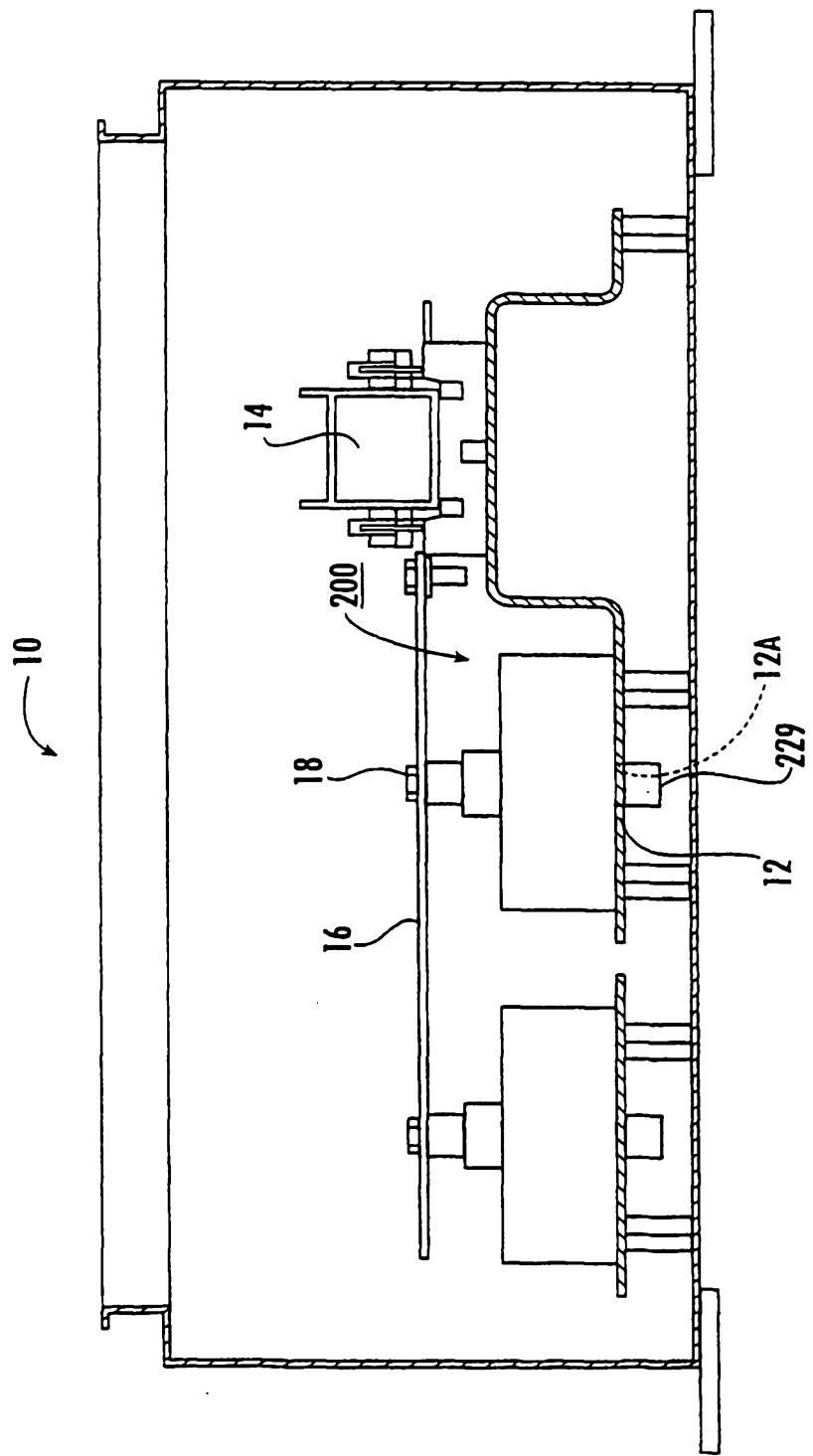
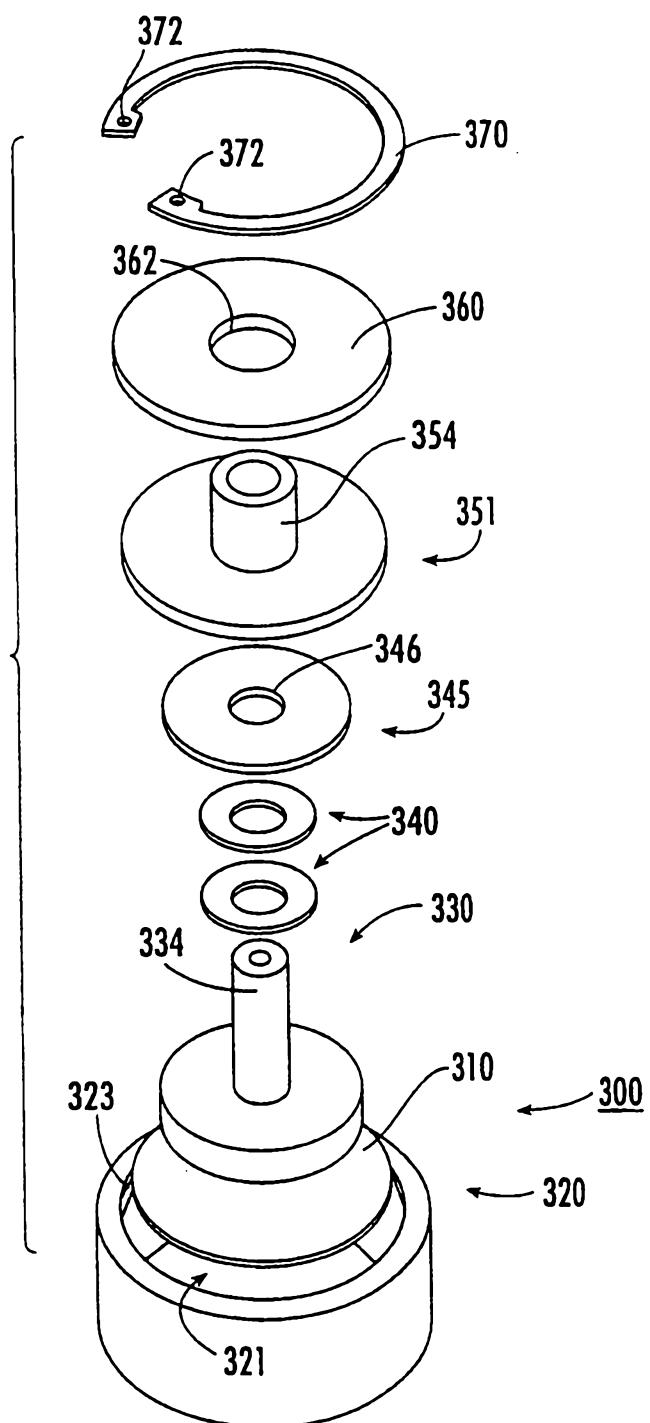


FIG. 8.

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FIG. 9.

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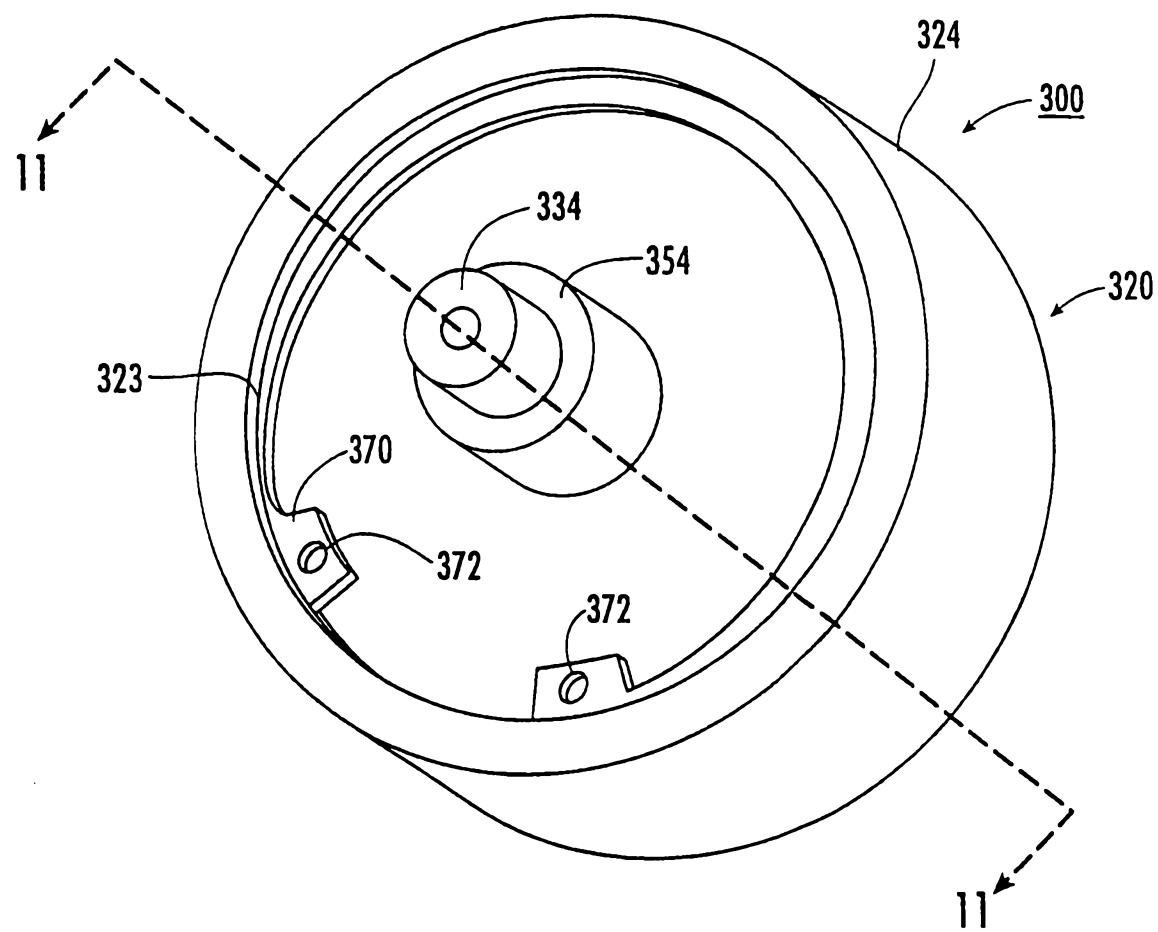


FIG. 10.

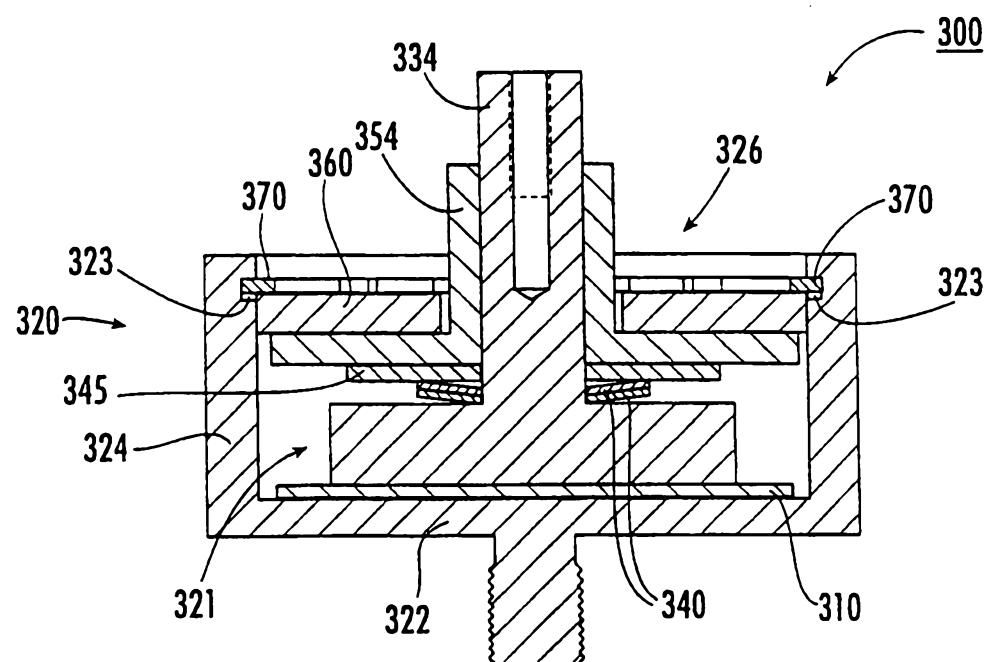


FIG. II.